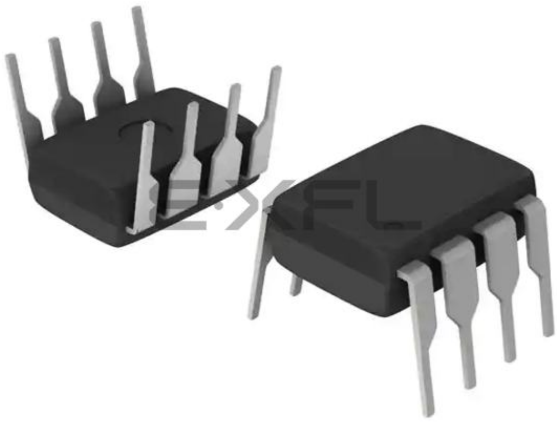


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f629-i-p

2.2.2.1 STATUS Register

The STATUS register, shown in Register 2-1, contains:

- the arithmetic status of the ALU
- the Reset status
- the bank select bits for data memory (SRAM)

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits, see the “Instruction Set Summary”.

> **Note 1:** Bits IRP and RP1 (STATUS<7:6>) are not used by the PIC12F629/675 and should be maintained as clear. Use of these bits is not recommended, since this may affect upward compatibility with future products.
>
> **2:** The C and DC bits operate as a $\overline{\text{Borrow}}$ and $\overline{\text{Digit Borrow}}$ out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS: STATUS REGISTER (ADDRESS: 03h OR 83h)

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **IRP:** This bit is reserved and should be maintained as ‘`0`’

bit 6 **RP1:** This bit is reserved and should be maintained as ‘`0`’

bit 5 **RP0:** Register Bank Select bit (used for direct addressing)
`0` = Bank 0 (00h - 7Fh)
`1` = Bank 1 (80h - FFh)

bit 4 **$\overline{\text{TO}}$:** Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT Time-out occurred

bit 3 **$\overline{\text{PD}}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
For borrow, the polarity is reversed.
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

bit 0 **C**: Carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{\text{borrow}}$ the polarity is reversed. A subtraction is executed by adding the two’s complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

2.2.2.4 PIE1 Register

The PIE1 register contains the interrupt enable bits, as shown in Register 2-4.

Note:	Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

REGISTER 2-4: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1 (ADDRESS: 8Ch)

R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	U-0	R/W-0
EEIE	ADIE	—	—	CMIE	—	—	TMR1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **EEIE:** EE Write Complete Interrupt Enable bit
1 = Enables the EE write complete interrupt
0 = Disables the EE write complete interrupt

bit 6 **ADIE:** A/D Converter Interrupt Enable bit (PIC12F675 only)
1 = Enables the A/D converter interrupt
0 = Disables the A/D converter interrupt

bit 5-4 **Unimplemented:** Read as ‘0’

bit 3 **CMIE:** Comparator Interrupt Enable bit
1 = Enables the comparator interrupt
0 = Disables the comparator interrupt

bit 2-1 **Unimplemented:** Read as ‘0’

bit 0 **TMR1IE:** TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

3.2.2 INTERRUPT-ON-CHANGE

Each of the GPIO pins is individually configurable as an interrupt-on-change pin. Control bits IOC enable or disable the interrupt function for each pin. Refer to Register 3-4. The interrupt-on-change is disabled on a Power-on Reset.

For enabled interrupt-on-change pins, the values are compared with the old value latched on the last read of GPIO. The 'mismatch' outputs of the last read are OR'd together to set, the GP Port Change Interrupt flag bit (GPIF) in the INTCON register.

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of GPIO. This will end the mismatch condition.

b) Clear the flag bit GPIF.

A mismatch condition will continue to set flag bit GPIF. Reading GPIO will end the mismatch condition and allow flag bit GPIF to be cleared.

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the GPIF interrupt flag may not get set.

REGISTER 3-4: IOC: INTERRUPT-ON-CHANGE GPIO REGISTER (ADDRESS: 96h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented**: Read as '0'

bit 5-0 **IOC<5:0>:** Interrupt-on-Change GPIO Control bits
1 = Interrupt-on-change enabled
0 = Interrupt-on-change disabled

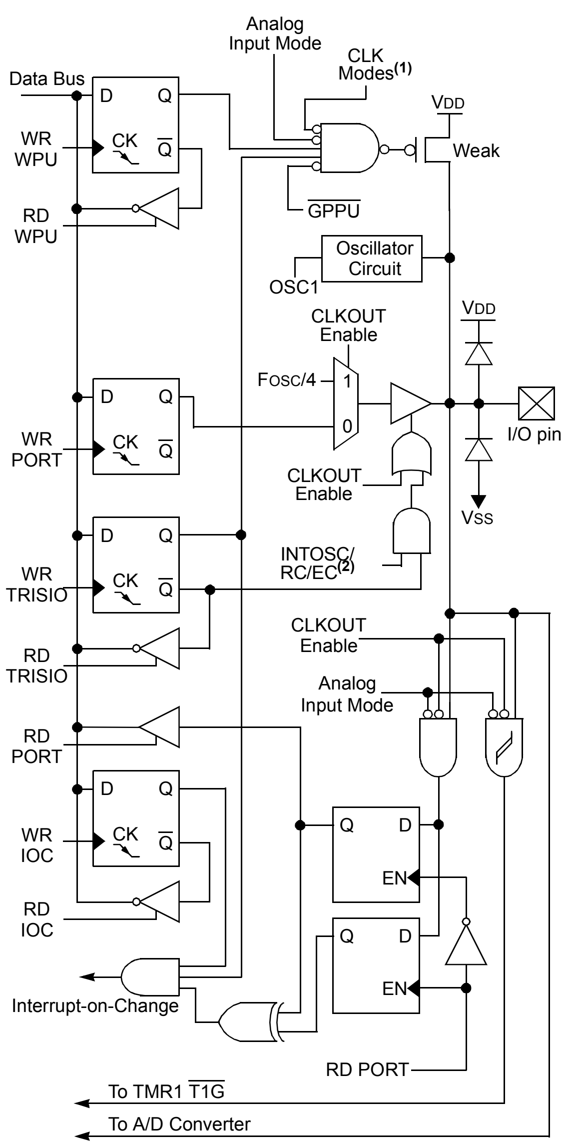
Note 1: Global Interrupt Enable (GIE) must be enabled for individual interrupts to be recognized.

3.3.5 GP4/AN3/$\overline{\text{T1G}}$/OSC2/CLKOUT

Figure 3-4 shows the diagram for this pin. The GP4 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D (PIC12F675 only)
- a TMR1 gate input
- a crystal/resonator connection
- a clock output

FIGURE 3-4: BLOCK DIAGRAM OF GP4



Note 1: CLK modes are XT, HS, LP, LPTMR1 and CLKOUT Enable.

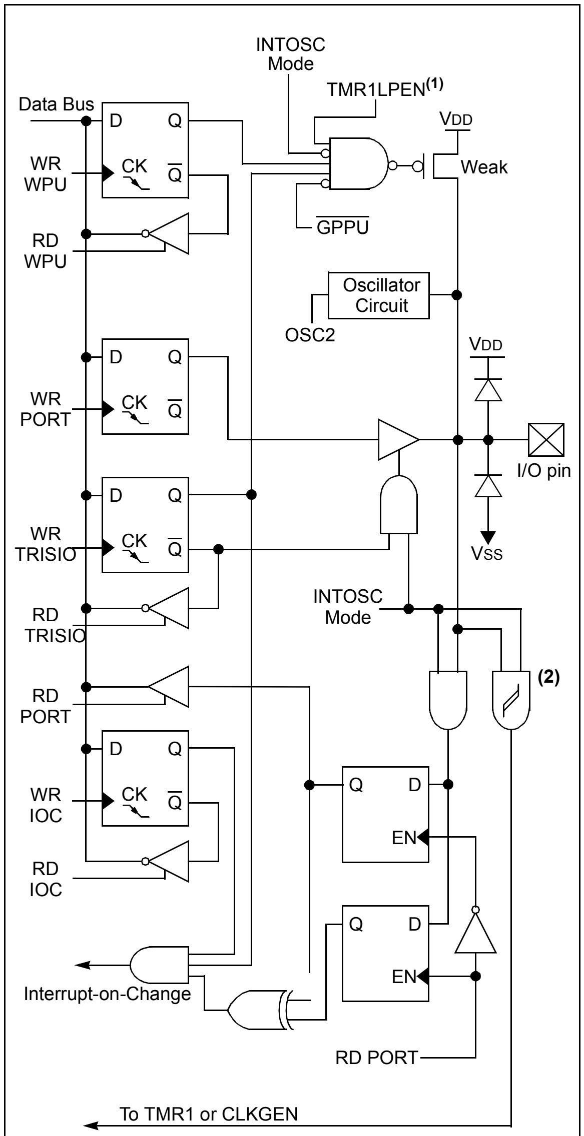
2: With CLKOUT option.

3.3.6 GP5/T1CKI/OSC1/CLKIN

Figure 3-5 shows the diagram for this pin. The GP5 pin is configurable to function as one of the following:

- a general purpose I/O
- a TMR1 clock input
- a crystal/resonator connection
- a clock input

FIGURE 3-5: BLOCK DIAGRAM OF GP5



Note 1: Timer1 LP Oscillator enabled

2: When using Timer1 with LP oscillator, the Schmitt Trigger is by-passed.

6.5 Comparator Reference

The comparator module also allows the selection of an internally generated voltage reference for one of the comparator inputs. The internal reference signal is used for four of the eight Comparator modes. The VRCON register, Register 6-2, controls the voltage reference module shown in Figure 6-5.

6.5.1 CONFIGURING THE VOLTAGE REFERENCE

The voltage reference can output 32 distinct voltage levels, 16 in a high range and 16 in a low range.

The following equations determine the output voltages:

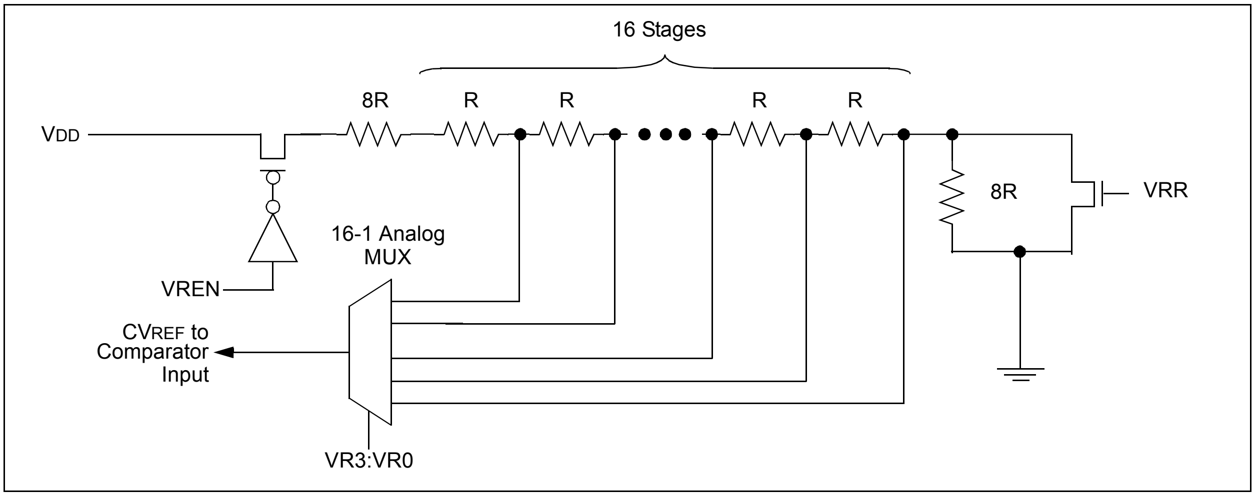
VRR = 1 (low range): $CV_{REF} = (VR3:VR0 / 24) \times V_{DD}$

VRR = 0 (high range): $CV_{REF} = (V_{DD} / 4) + (VR3:VR0 \times V_{DD} / 32)$

6.5.2 VOLTAGE REFERENCE ACCURACY/ERROR

The full range of V_{SS} to V_{DD} cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 6-5) keep CV_{REF} from approaching V_{SS} or V_{DD}. The Voltage Reference is V_{DD} derived and therefore, the CV_{REF} output changes with fluctuations in V_{DD}. The tested absolute accuracy of the Comparator Voltage Reference can be found in **Section 12.0 "Electrical Specifications"**.

FIGURE 6-5: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



6.6 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output is ensured to have a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise, the maximum delay of the comparators should be used (Table 12-7).

6.7 Operation During Sleep

Both the comparator and voltage reference, if enabled before entering Sleep mode, remain active during Sleep. This results in higher Sleep currents than shown in the power-down specifications. The additional current consumed by the comparator and the voltage reference is shown separately in the specifications. To minimize power consumption while in Sleep mode, turn off the comparator, CM2:CM0 = `111`, and voltage reference, VRCON<7> = `0`.

While the comparator is enabled during Sleep, an interrupt will wake-up the device. If the device wakes up from Sleep, the contents of the CMCON and VRCON registers are not affected.

6.8 Effects of a Reset

A device Reset forces the CMCON and VRCON registers to their Reset states. This forces the comparator module to be in the Comparator Reset mode, CM2:CM0 = `000` and the voltage reference to its off state. Thus, all potential inputs are analog inputs with the comparator and voltage reference disabled to consume the smallest current possible.

TABLE 7-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Device Frequency			
Operation	**ADCS2:ADCS0**	**20 MHz**	**5 MHz**	**4 MHz**	**1.25 MHz**
2 TOSC	000	100 ns(2)	400 ns(2)	500 ns(2)	1.6 μs
4 TOSC	100	200 ns(2)	800 ns(2)	1.0 μs(2)	3.2 μs
8 TOSC	001	400 ns(2)	1.6 μs	2.0 μs	6.4 μs
16 TOSC	101	800 ns(2)	3.2 μs	4.0 μs	12.8 μs(3)
32 TOSC	010	1.6 μs	6.4 μs	8.0 μs(3)	25.6 μs(3)
64 TOSC	110	3.2 μs	12.8 μs(3)	16.0 μs(3)	51.2 μs(3)
A/D RC	x11	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The A/D RC source has a typical TAD time of 4 μs for VDD > 3.0V.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the A/D RC clock source is only recommended if the conversion will be performed during Sleep.

7.1.5 STARTING A CONVERSION

The A/D conversion is initiated by setting the GO/$\overline{\text{DONE}}$ bit (ADCON0<1>). When the conversion is complete, the A/D module:

- Clears the GO/$\overline{\text{DONE}}$ bit
- Sets the ADIF flag (PIR1<6>)
- Generates an interrupt (if enabled)

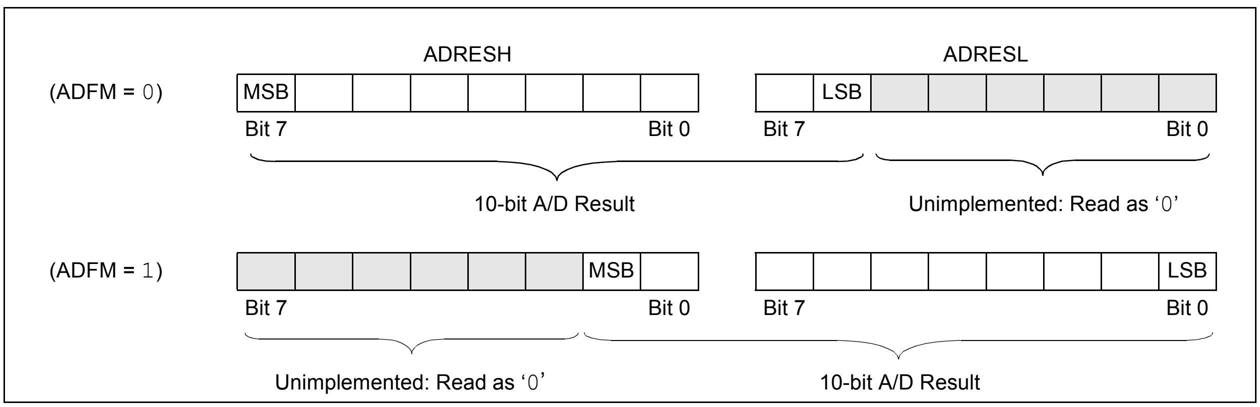
If the conversion must be aborted, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete A/D conversion sample. Instead, the ADRESH:ADRESL registers will retain the value of the previous conversion. After an aborted conversion, a 2 TAD delay is required before another acquisition can be initiated. Following the delay, an input acquisition is automatically started on the selected channel.

Note:	The GO/$\overline{\text{DONE}}$ bit should not be set in the same instruction that turns on the A/D.

7.1.6 CONVERSION OUTPUT

The A/D conversion can be supplied in two formats: left or right shifted. The ADFM bit (ADCON0<7>) controls the output format. Figure 7-2 shows the output formats.

FIGURE 7-2: 10-BIT A/D RESULT FORMAT



8.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full VDD range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC12F629/675 devices have 128 bytes of data EEPROM with an address range from 0h to 7Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature as well as from chip to chip. Please refer to AC Specifications for exact limits.

When the data memory is code-protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the data EEPROM is available in the PIC® Mid-Range Reference Manual, (DS33023).

REGISTER 8-1: EEDAT: EEPROM DATA REGISTER (ADDRESS: 9Ah)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-0 **EEDATn**: Byte value to write to or read from data EEPROM

REGISTER 8-2: EEADR: EEPROM ADDRESS REGISTER (ADDRESS: 9Bh)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	EADR6	EADR5	EADR4	EADR3	EADR2	EADR1	EADR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented**: Should be set to ‘0’

bit 6-0 **EEADR**: Specifies one of 128 locations for EEPROM Read/Write Operation

FIGURE 9-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

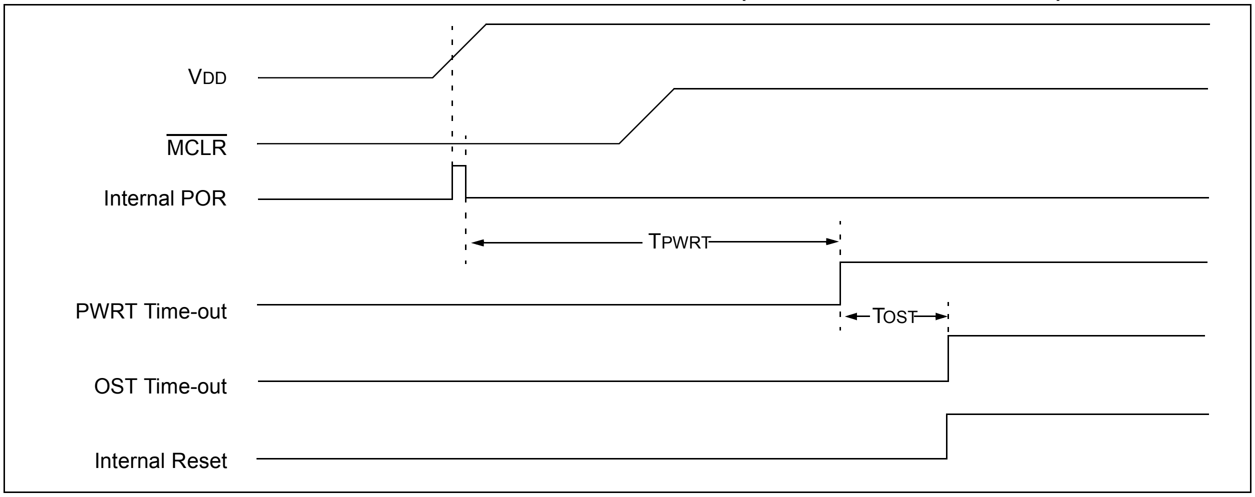


FIGURE 9-8: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

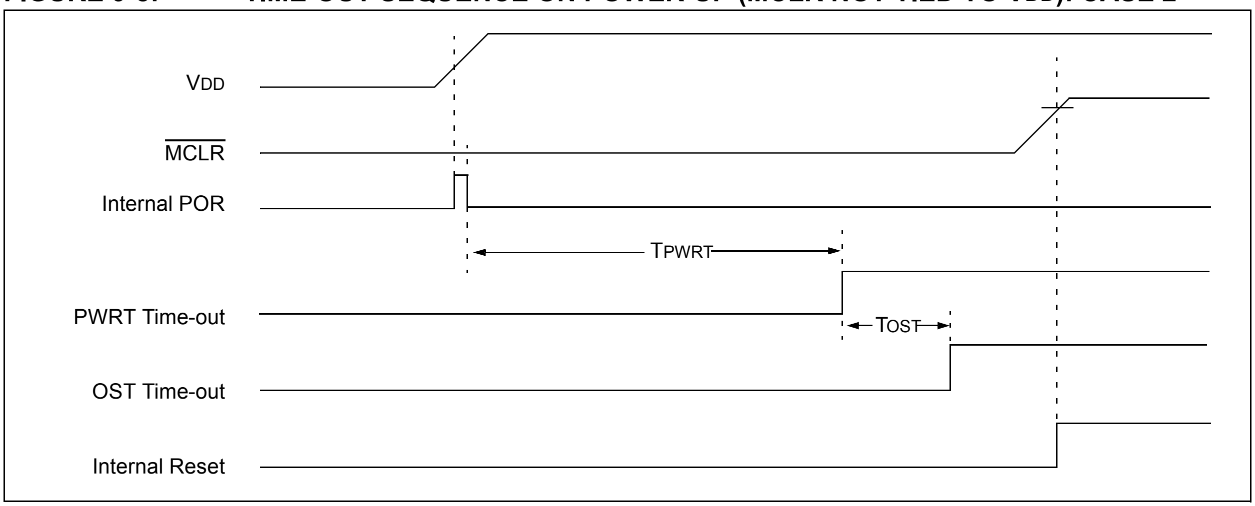
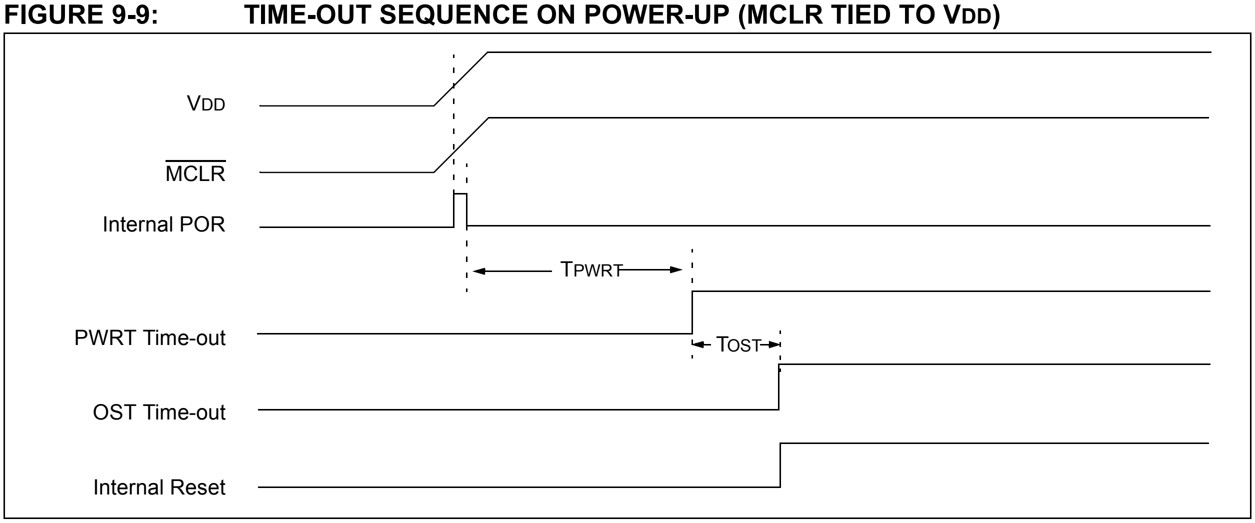


FIGURE 9-9: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})



BTFSC	Bit Test, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	$0 \leq f \leq 127$ $0 \leq b \leq 7$
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit ‘b’ in register ‘f’ is ‘`1`’, the next instruction is executed. If bit ‘b’, in register ‘f’, is ‘`0`’, the next instruction is discarded, and a `NOP` is executed instead, making this a 2TCY instruction.

CALL	Call Subroutine
Syntax:	[*label*] CALL k
Operands:	$0 \leq k \leq 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. `CALL` is a two-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \leq f \leq 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register ‘f’ are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	`CLRWDT` instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(\bar{f})$ → (destination)
Status Affected:	Z
Description:	The contents of register ‘f’ are complemented. If ‘d’ is `0`, the result is stored in W. If ‘d’ is `1`, the result is stored back in register ‘f’.

DECF	Decrement f
Syntax:	[*label*] DECF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register ‘f’. If ‘d’ is `0`, the result is stored in the W register. If ‘d’ is `1`, the result is stored back in register ‘f’.

MOVF — Move f

Syntax:	[*label*] MOVF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(f) \rightarrow$ (dest)
Status Affected:	Z
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = 0, the destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	`MOVF FSR, 0` After Instruction W = value in FSR register Z = 1

MOVLW — Move literal to W

Syntax:	[*label*] MOVLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k \rightarrow (W)$
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.
Words:	1
Cycles:	1
Example:	`MOVLW 0x5A` After Instruction W = 0x5A

MOVWF — Move W to f

Syntax:	[*label*] MOVWF f
Operands:	$0 \leq f \leq 127$
Operation:	$(W) \rightarrow (f)$
Status Affected:	None
Description:	Move data from W register to register 'f'.
Words:	1
Cycles:	1
Example:	`MOVWF OPTION` Before Instruction OPTION = 0xFF W = 0x4F After Instruction OPTION = 0x4F W = 0x4F

NOP — No Operation

Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.
Words:	1
Cycles:	1
Example:	`NOP`

RETFIE	Return from Interrupt
Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None
Description:	Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example:	`RETFIE` After Interrupt PC = TOS GIE = 1

RETLW	Return with literal in W
Syntax:	[*label*] RETLW k
Operands:	$0 \leq k \leq 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the eight-bit literal ‘k’. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example:	see below

```
        CALL TABLE;W contains
        table
            ;offset value
TABLE   •   ;W now has table value
        •
        •
        ADDWF PCL ;W = offset
        RETLW k1  ;Begin table
        RETLW k2  ;
        •
        •
        •
        RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN	Return from Subroutine
Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .XOR. k $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

NOTES:

12.1 DC Characteristics: PIC12F629/675-I (Industrial), PIC12F629/675-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					FOSC < = 4 MHz:
D001			2.0	—	5.5	V	PIC12F629/675 with A/D off
D001A			2.2	—	5.5	V	PIC12F675 with A/D on, 0°C to +125°C
D001B			2.5	—	5.5	V	PIC12F675 with A/D on, -40°C to +125°C
D001C			3.0	—	5.5	V	4 MHz < FOSC < = 10 MHz
D001D			4.5	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage**(1)	1.5*	—	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOD		—	2.1	—	V	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

12.7 DC Characteristics: PIC12F629/675-I (Industrial), PIC12F629/675-E (Extended) (Cont.)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15*	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins	—	—	50*	pF	
		Data EEPROM Memory					
D120	ED	Byte Endurance	100K	1M	—	E/W	-40°C ≤ TA ≤ +85°C
D120A	ED	Byte Endurance	10K	100K	—	E/W	+85°C ≤ TA ≤ +125°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write cycle time	—	5	6	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(1)	1M	10M	—	E/W	-40°C ≤ TA ≤ +85°C
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C ≤ TA ≤ +85°C
D130A	ED	Cell Endurance	1K	10K	—	E/W	+85°C ≤ TA ≤ +125°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VPEW	VDD for Erase/Write	4.5	—	5.5	V	
D133	TPEW	Erase/Write cycle time	—	2	2.5	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: See **Section 8.5.1 "Using the Data EEPROM"** for additional information.

FIGURE 12-6: CLKOUT AND I/O TIMING

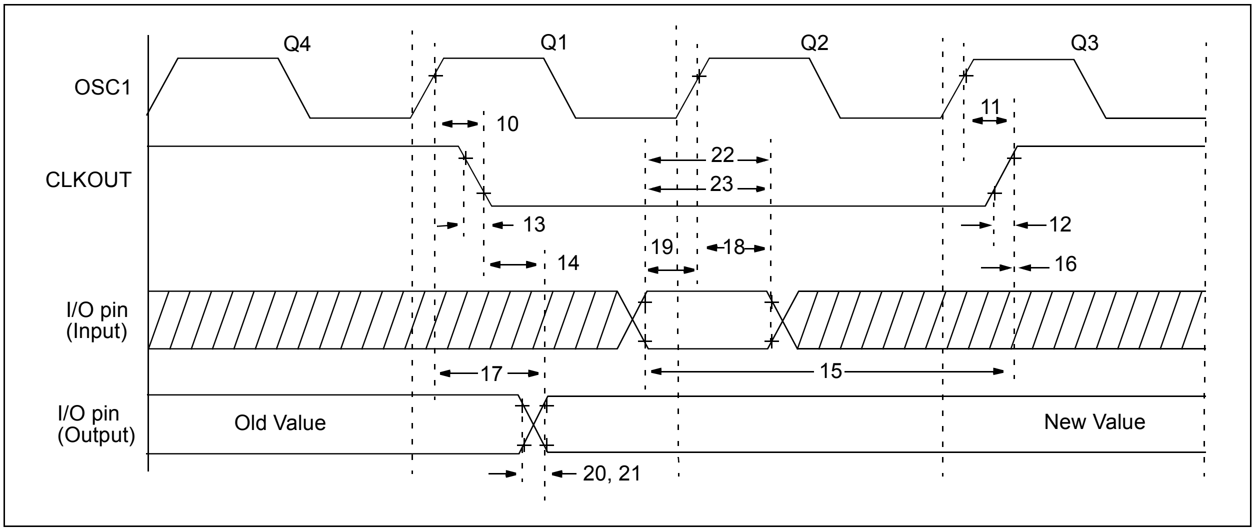


TABLE 12-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLOUT↓	—	75	200	ns	**(Note 1)**
11	TosH2ckH	OSC1↑ to CLOUT↑	—	75	200	ns	**(Note 1)**
12	TckR	CLKOUT rise time	—	35	100	ns	**(Note 1)**
13	TckF	CLKOUT fall time	—	35	100	ns	**(Note 1)**
14	TckL2ioV	CLKOUT↓ to Port out valid	—	—	20	ns	**(Note 1)**
15	TioV2ckH	Port in valid before CLKOUT↑	TOSC + 200 ns	—	—	ns	**(Note 1)**
16	TckH2ioI	Port in hold after CLKOUT↑	0	—	—	ns	**(Note 1)**
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	50	150 *	ns	
			—	—	300	ns	
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	100	—	—	ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20	TioR	Port output rise time	—	10	40	ns	
21	TioF	Port output fall time	—	10	40	ns	
22	Tinp	INT pin high or low time	25	—	—	ns	
23	Trbp	GPIO change INT high or low time	TCY	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4xTOSC.

FIGURE 13-13: TYPICAL IPD WITH CVREF ENABLED vs. VDD OVER TEMP (-40°C TO +125°C)

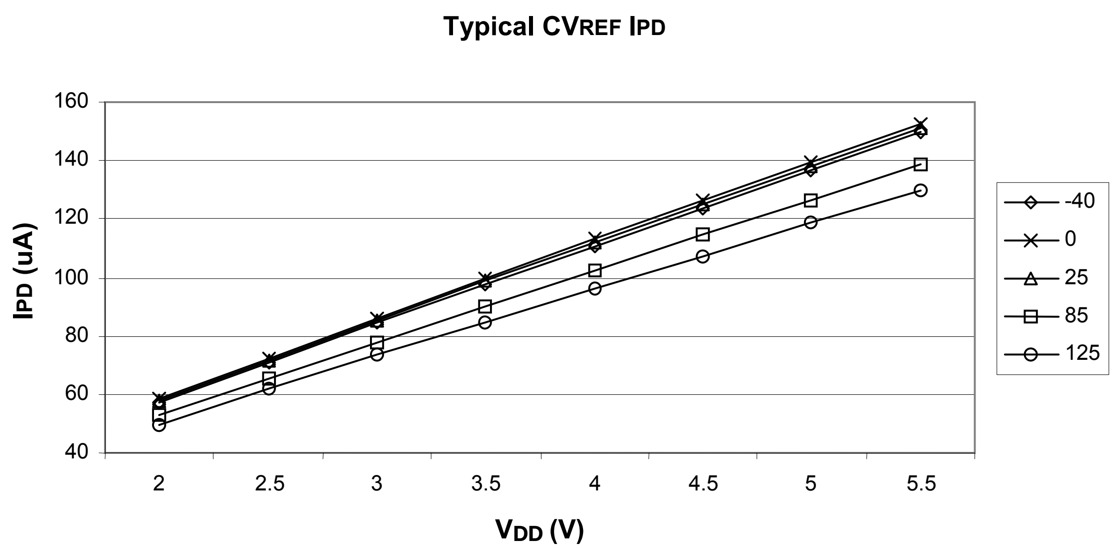
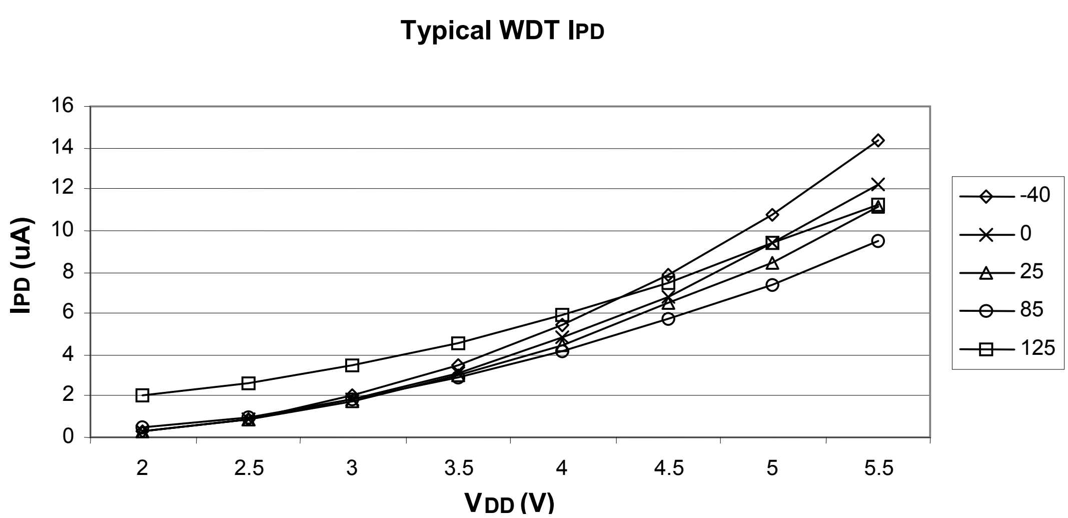
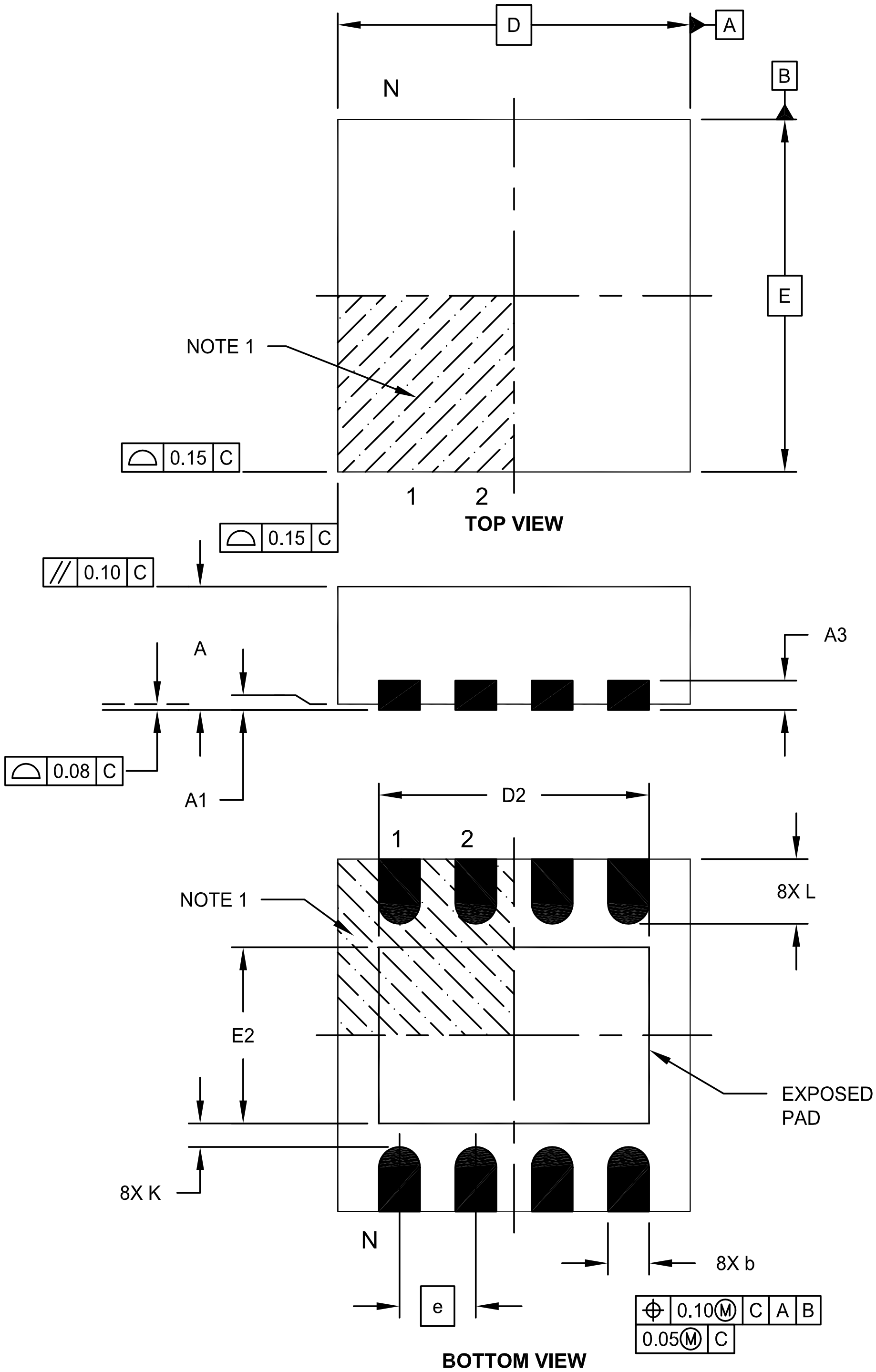


FIGURE 13-14: TYPICAL IPD WITH WDT ENABLED vs. VDD OVER TEMP (-40°C TO +125°C)



8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-131E Sheet 1 of 2

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A

This is a new data sheet.

Revision B

Added characterization graphs.

Updated specifications.

Added notes to indicate Microchip programmers maintain all Calibration bits to factory settings and the PIC12F675 ANSEL register must be initialized to configure pins as digital I/O.

Updated MLF-S package name to DFN-S.

Revision C

Revision D (01/2007)

Updated Package Drawings; Replace PICmicro with PIC; Revised Product ID example (b).

Revision E (03/2007)

Replaced Package Drawings (Rev. AM); Replaced Development Support Section.

Revision F (09/2009)

Updated Registers to new format; Added information to the “Package Marking Information” (8-Lead DFN) and “Package Details” sections (8-Lead Dual Flat, No Lead Package (MD) 4X4X0.9 mm Body (DFN)); Added Land Patterns for SOIC (SN) and DFN-S (MF) packages; Updated Register 3-2; Added MD Package to the Product identification System chapter; Other minor corrections.

Revision G (03/2010)

Updated the Instruction Set Summary section, adding pages 76 and 77.

APPENDIX B: DEVICE DIFFERENCES

The differences between the PIC12F629/675 devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Feature	PIC12F629	PIC12F675
A/D	No	Yes

NOTES: